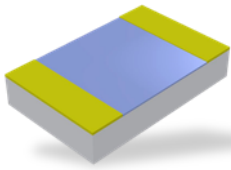
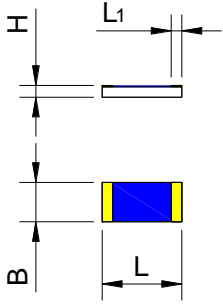



Platinum-Resistance-Temperature-Detector: CRFSMD Series

Two baked-in glass cover layers reliably protect the platinum layer from external influences. Platinum Flip-chip temperature sensors designed for „Face-down“ installation in temperature ranges from -50°C ... +150°C. If suitable connection techniques are used, the temperature sensors can even use in a range from -70°C ... +250°C. Adherence to tolerance limits then has to check according to the application. The connection technology and housing selected by the customer determine the thermal resistance.

Type	CRFSMD Series „Face-down“		  
Operating temperature range	-70°C ... +250°C		
Temperature validity range DIN EN 60571	B (F 0.3)	-50°C ... +250°C	
Resistance value	Pt100 Pt500 Pt1000		
Measuring/maximum current	Pt100: 1 mA ... 7 mA Pt500: 0.7 mA ... 3 mA Pt1000: 0.1 mA ... 1 mA		
Temperature coefficient	3850 ppm/K		
Long-term stability	max. R ₀ -drift 0,05 %/year		
Storage	5 years under normal ambient conditions		
Processing notes	All forms of reflow soldering are preferred		
Packaging	Packaging unit of 5,000 pieces in an 8-mm belt on a 7" plastic reel with roll feed line Small quantity without roll feed line		

Available models												
Temperature sensor						Connection		PU in tape & reel	Tolerance class			
Type	R ₀ /Ω	Design	B	L	H	Material	L1		1/3B	A	B	
CRFSMD-0805-100	100	0805	1.25	2.0	0.4	Au-plated Ni	0.5	5.000			●	
CRFSMD-0805-500	500	0805	1.25	2.0	0.4	Au-plated Ni	0.5	5.000			●	
CRFSMD-0805-1000	1000	0805	1.25	2.0	0.4	Au-plated Ni	0.5	5.000			●	

Dimensional tolerances: ΔB = +0.2; -0.1 / ΔL = +0.2; -0.1 / ΔH = ± 0.1 // ΔL1 = +0.1; -0.2

Dimensions in mm

Self-heating coefficients and response times					
Type	Self-heating coefficient E in K/mW		Response times in seconds		
	Water (v ≥ 0.2 m/s)		in Water (v = 0.4 m/s)		in Air (v = 1 m/s)
			t _{0.5}	t _{0.9}	t _{0.5}
CRSMD-0805-100	0.15		0.1	0.3	2.6
CRSMD-0805-500	0.15		0.1	0.3	2.6
CRSMD-0805-1000	0.15		0.1	0.3	2.6

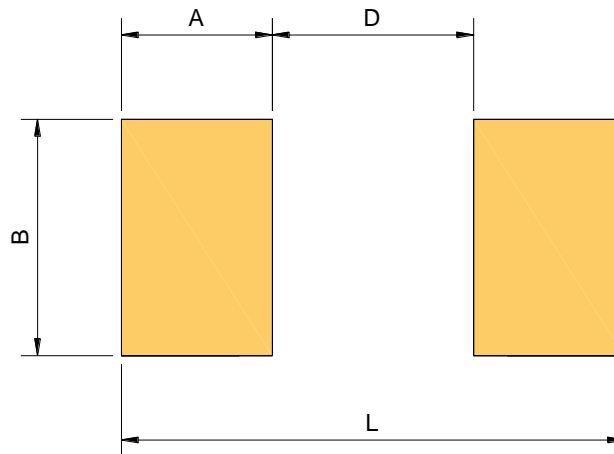
Processing notes

All forms of reflow soldering are preferred. The temperature sensors could be damaged when soldering with a soldering iron. The manufacturer has tested lead-free SAC solder as well as leaded standard solder (up to 95 % Pb). The soldering temperature can be raised slightly in comparison to tin-plated components.

Type CRFSMD (flip chip): Depending on the solder used, it may be necessary to adapt the printed solder quantity compared to a sensor/component with wrap-around contact.

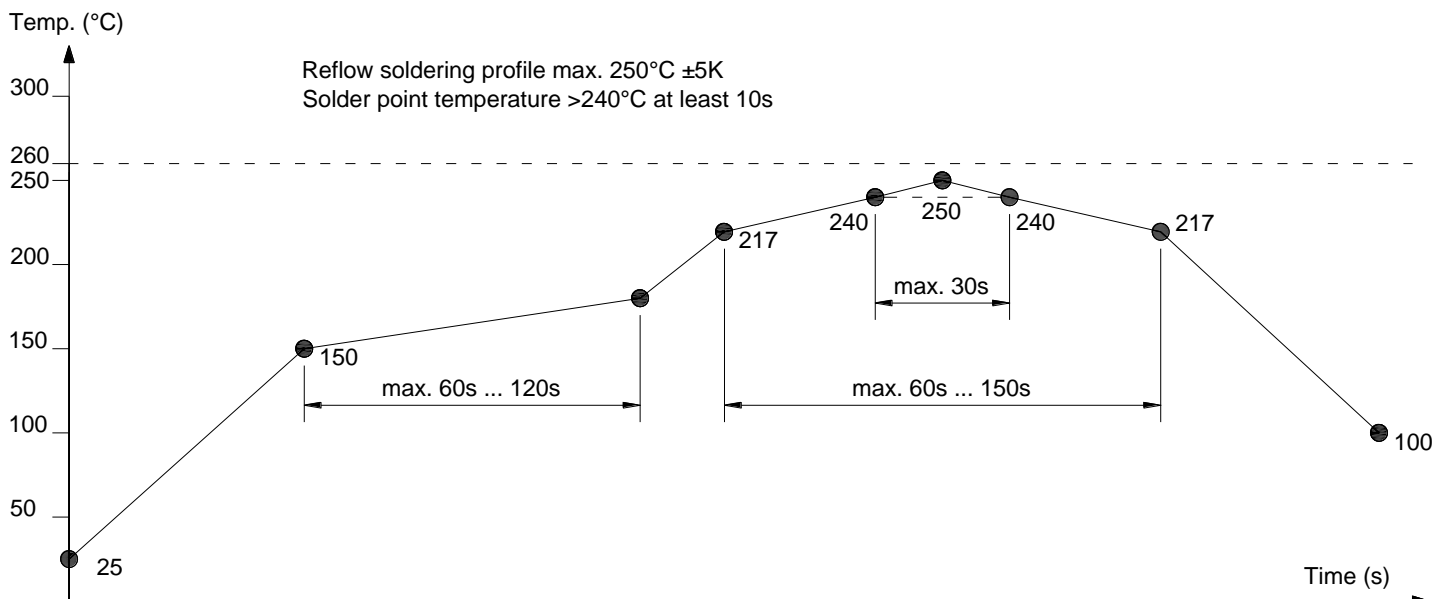
Application of the metallized top side: Optimized for soft-soldering in a reflow method.

Recommended pad dimensions on the circuit board



Type	Design (imperial)	Design (metric)	A (mm)	B (mm)	D (mm)	L (mm)
CRSMD-0805	0805	2012M	0.80	1.25	1.00	2.60
CRSMD-1206	1206	3216M	0.80	1.50	2.00	3.60
CRFSMD-0805	0805	2012M	0.65	1.25	0.90	2.20

Recommended soldering profile for lead-free solder, type SAC 305/405



Changes and errors excepted

Application Notes for Platinum-Chip Temperature Sensors

1. Introduction

Thin-film platinum chip temperature sensors from Alpha Thermo are basically formed from a ceramic substrate on which a thin structured layer of platinum is applied. A glass layer seals off the platinum layer and protects the temperature sensor to a certain extent from chemical and mechanical influences. During subsequent fabrication of the materials that are used, and the type and method of the processing, have a decisive effect on the functionality and long-term stability of the temperature sensors. In specific cases, it may be necessary to carry out qualification tests for a selected design, to ensure that technical specifications for measurement accuracy are met over the temperature range of application. The following application notes have been put together by Alpha Thermo as a result of many years of experience in processing and handling platinum chip temperature sensors and are to be taken as recommendations.

2. Mechanical strength of the connecting wires

2.1. Wired Platinum-Chip Temperature Sensors

The connecting wires of the temperature sensors can be subjected to the maximum tensions shown below, without the functionality being affected. Ensure that the wires are not loaded laterally. Please refer to the data sheet for the maximum admissible horizontal tensile load on one individual wire. If the connecting wires have to be bent, care must be taken that the bend is not made directly at the point where the connecting wire enters the component sealing. If necessary, use a suitable tool to keep the mechanical stress away from this point. Connections of the connecting wires, or tight bends, must also be avoided, since this not only increases the resistance (leading to a systematically higher temperature indication) but also makes the wires fragile and liable to break under temperature stress.

2.2. CRKL Series

These temperature sensors have terminals which are soldered on and especially it is therefore particularly important that the connections are not subjected to a sideways loading during processing. The maximum permissible horizontal tension is 10 newtons per terminal clamp. Bending or kinking of the terminal clamps is not permissible.

3. Connection methods

Basically, the connecting wires of the temperature sensors can be fabricated with all the connection methods. These are: soft soldering, brazing, crimping, resistance welding, laser welding. In practice, the relevant parameters for a good connection vary according to the type used (see data sheet). It is therefore advisable to make some test welds to obtain the best results. During welding or soldering, care must be taken that there is no concentrated heating of the sealing points of the connecting wires. If this occurs, the differences in thermal expansion of the materials can lead to strains or cracks and thus failure later on. Furthermore, the maximum operating temperature of the temperature sensors must not be exceeded during handling and processing. It is recommended that a heat sink or similar tool is used to prevent excessive heat reaching the temperature sensor. The connecting wires should also note that the nominal values are valid for the standard length of connecting wires, whereby the point of measurement is always 2 mm from the open end of the connecting wires. Alteration to the length of the connecting wires will change

the resistance. This may have the effect that the tolerance class limits are no longer met.

4. Mounting and installation

4.1. Handling

Soft plastic clamps or tweezers should be used for handling temperature sensors. Micro or coarse gripping/clamping devices can cause damage to the temperature sensors.

4.2. Potting, coating and gluing

During production processing of platinum chip temperature sensors, it is important to avoid any mechanical stresses between the temperature sensor and the potting compound or casting resin, which arise from the difference between the coefficients of thermal expansion of the various materials that are used. It is therefore advantageous to use potting compounds that retain elasticity after hardening. If not, it cannot be ruled out that signal shifts may occur, or even a total failure of the temperature sensor. In extreme cases, potting compounds and adhesives should therefore be qualified by testing before being used for series production. For instance, we recommend temperature cycling over the intended temperature range of the application. Care must be taken that the potting or coating compounds provide electrical insulation and are chemically neutral with regard to the temperature sensor (ceramic substrate material [Al₂O₃] and various glass materials). The upper operating limit for the temperature sensor must also not be exceeded during drying/hardening process. When the temperature sensor is placed in the protection tube and positioned, care must be taken that there is sufficient clearance between the sensor and the wall of the tube. If the sensor is skewed or fitted too tightly, it may be damaged.

4.3. Surface mounting

Platinum chip temperature sensors can be affixed to flat surfaces by using various types of (SMD) adhesive, or double-sided adhesive tapes. The usual curing/hardening methods (UV radiation and/or heat) do not create critical stresses for the sensors. The notes of 2 must be observed.

4.4. Unprotected application

The sealing (glass covering) and connecting of the sensors may be damaged if they are exposed to a corrosive atmosphere, especially in conjunction with moisture. Platinum chip temperature sensors should therefore not be used in such an environment without protection. In bare sensors cannot be avoided, for instance in HVAC applications, we recommend using our M series, or sensors that have been sealed by an additional protective coating. In this case, it is absolutely vital that the sensor carries out an appropriate qualification test of the functionality and operating life.

5. Thermal characteristics

5.1. Response times

We measure the response times of platinum chip temperature sensors in agitated water flow with a velocity of $v = 0.2$ meters/second, and the average values are $t_{0.5} = 0.2$ sec and $t_{0.9} = 0.4$ sec. Subsequent fabrication, such as installation protection tube, will increase the response times, depending on the nature and the materials that are used. Care must therefore be taken to ensure good heat transfer between the temperature sensor and the protection tube. Heat conductive pastes and alumina powder have proved suitable as heat conducting materials.

5.2. Self-heating

In order to measure the electrical resistance, current must flow through the temperature sensor. This current will heat up the temperature sensors by an amount that can be smaller, depending on external factors. The size of the resulting error caused by self-heating depends on the applied power $P = I^2 \times R$, the amount of heat that is removed by the medium being measured, the conductivity of the temperature sensor and its surface. These specific characteristics combined in the self-heating coefficient E , that the error caused by self-heating is given by $\Delta t = I^2 \times R \times E$. Self-heating coefficients of platinum chip temperature sensors are measured in air at $v = 2$ m/sec and agitated water at $v = 0.2$ m/sec. The average coefficients are 0.12 °C/mW, in water 0.02 °C/mW. For precise details on items 5.1 and 5.2 can be found in the appropriate data sheets.

5.3. Measuring current

To avoid self-heating effects and possible damage to the temperature sensors, we recommend the following maximum currents:

- ≤ 1.0 mA for Pt100 temperature sensors,
- ≤ 0.7 mA for Pt500 temperature sensors, and
- ≤ 0.1 mA for Pt1000 temperature sensors.

6. Cleaning

Our temperature sensors come ready cleaned from the factory. Further cleaning is normally required. However, if additional cleaning operations are necessary during processing, then the sensors can be cleaned in baths containing mild cleaning agents, such as ethanol. A quick cleaning by ultrasonics is also permissible.

7. Storage

In the (standard) belt packaging, temperature sensors can be stored for several months in a normal environment. But storage in a corrosive atmosphere or corrosive medium or under high humidity conditions is not permissible.

8. Delivered quality

The electrical characteristics of temperature sensors are 100% tested in accordance with EN 60751 during manufacture with a measurement uncertainty of 0.03% (95% confidence interval) for the tolerance classes. The testing procedure includes the mechanical strength of the connecting wires and the conformity to dimensional tolerances. After tolerance selection and cleaning (standard) temperature sensors are individually packaged and stored for dispatch in high quality, comprehensive information and fast delivery capability are just a few of the advantages of using temperature sensors.